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## ROUND TYPE LED LAMPS

### LSBK2042S

## DATA SHEET

DOC. NO : QW0905-LSBK2042S

REV. : A

DATE : 17 - Jan - 2005



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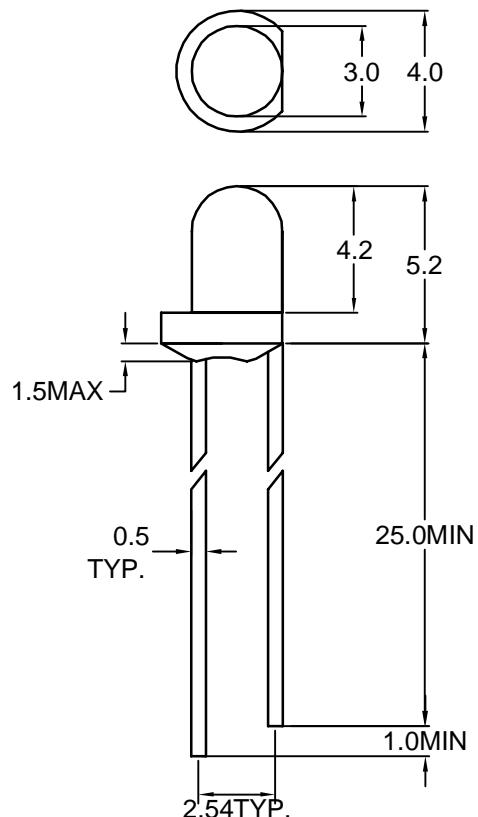
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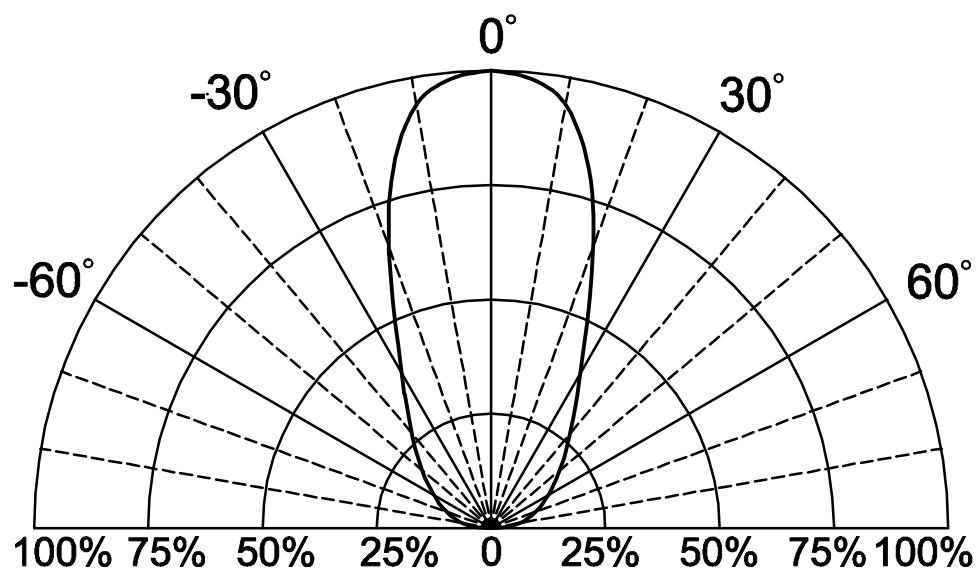
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### Package Dimensions



Note : 1. All dimension are in millimeter tolerance is  $\pm 0.25\text{mm}$  unless otherwise noted.  
2. Specifications are subject to change without notice.

### Directivity Radiation





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## Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Ratings	UNIT
		SBKS	
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current Duty 1/10@10KHz	I <sub>FP</sub>	100	mA
Power Dissipation	PD	120	mW
Reverse Current @5V	I <sub>r</sub>	50	µ A
Electrostatic Discharge	ESD	500	V
Operating Temperature	T <sub>opr</sub>	-20 ~ +80	
Storage Temperature	T <sub>stg</sub>	-30 ~ +100	
Soldering Temperature	T <sub>sol</sub>	Max 260 for 5 sec Max (2mm from body)	

## Typical Electrical &amp; Optical Characteristics (Ta=25 )

PART NO	MATERIAL	COLOR		Dominant wave length Dnm	Spectral halfwidth nm	Forward voltage @20mA(V)		Luminous intensity @20mA(mcd)		Viewing angle 2 1/2 (deg)
		Emitted	Lens			Typ.	Max.	Min.	Typ.	
LSBK2042S	InGaN/SiC	Blue	White Diffused	475	26	3.5	4.2	220	550	50

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.

2. The luminous intensity data did not including ±15% testing tolerance.



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## Typical Electro-Optical Characteristics Curve

SBK CHIP

Fig.1 Forward current vs. Forward Voltage

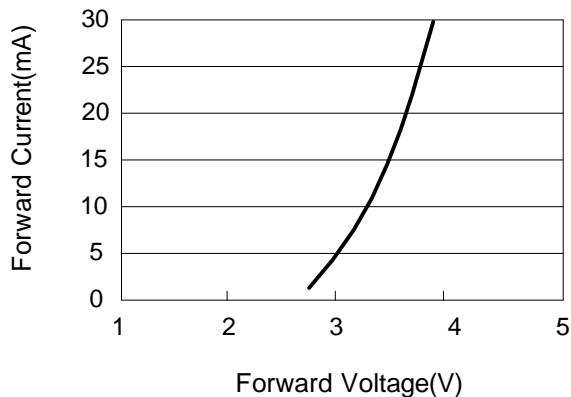


Fig.2 Relative Intensity vs. Forward Current

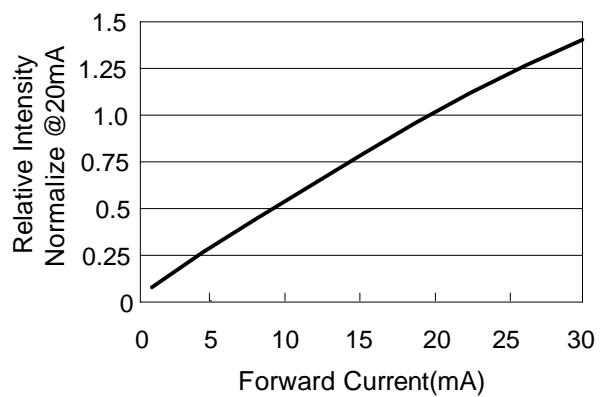


Fig.3 Forward Current vs. Temperature

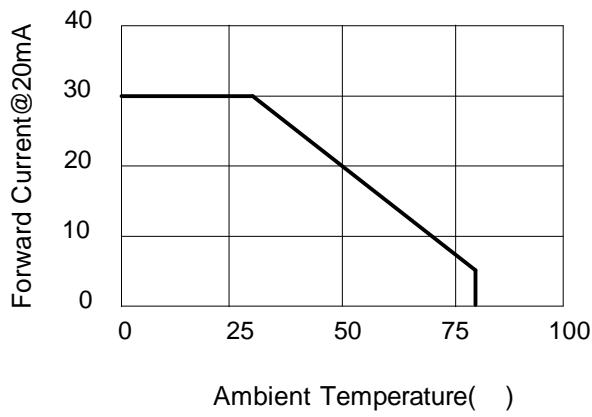
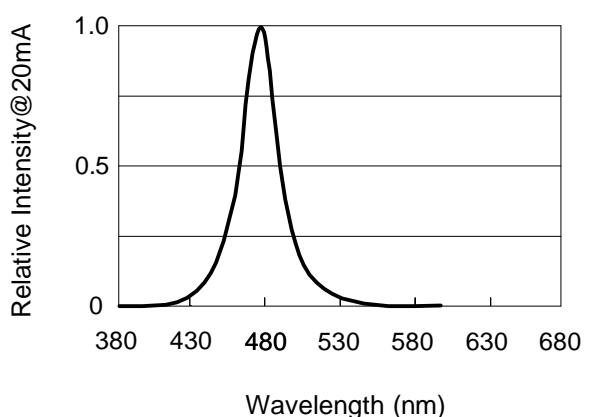


Fig.4 Relative Intensity vs. Wavelength





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**Reliability Test:**

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 ±5 2.RH=90 %~95 % 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 ±5 &-40 ±5 (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 ±5 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 ±5 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2